

NEXT GENERATION MK7 REFLOW OVEN

The Thermal Technology Leader in Semicon and SMT

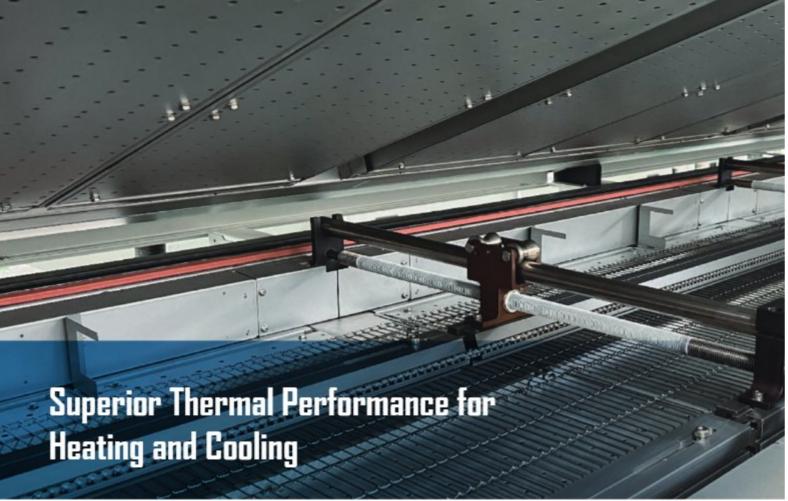








The Thermal Technology Leader in Semicon and SMT



The New MK7 platform has revolutionized the reflow industry with several new and groundbreaking designs. The low-profile modules provide lower Delta T while reducing overall energy consumption. New flux management options offer exceptional capability and reduce overall PM times. New cooling systems offer best in class cooling rates and low exit temperatures while providing exceptional thermal separation between zones. We invite you to visit any one of our 3 demo locations to run profiles and see for yourself the strong advantages the MK7 can bring to your process. Or if you prefer, send us your toughest board and we will run profiles and generate the data for you. We are happy to work with you to create a custom configuration to fit your needs.

NEW HEATING SYSTEM

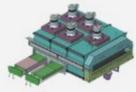
Enhanced low height heater module and large impeller provides the lowest delta T's on product with improved air flow and uniformity!



NEW COOLING SYSTEM

A variety of module types and systems are available, tailored to the application including the most demanding lead-free profile requirements. A super cooling system option is available for high mass applications that can provide cooling rates >6°C/sec and exit temperatures below 50°C.



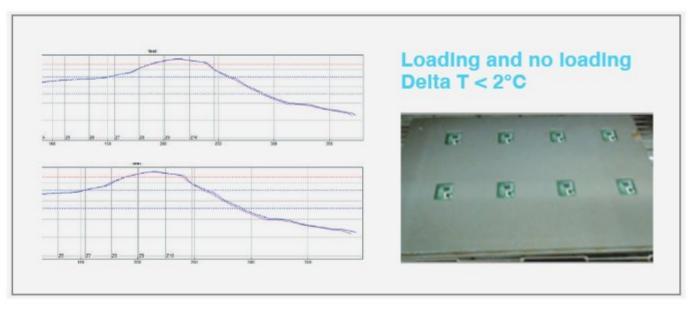


Water Type Cooling Module

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Excellent thermal performance is achieved with improved designs for heating and dynamic control, while energy usage is reduced with improved sealing and insulation. The Energy Management System on MK7 ovens provides smart control when off-loading of production to further save energy consumption.

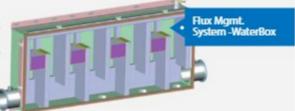




Slow down chain speed



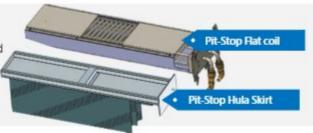
Due to the new heat exchanger design with chilled water, the water box flux management system gives superb flux filtration performance while keeping maintenance and cleaning easy during PM. The enlarged capacity of provides longer interval between PM than other flux management systems.



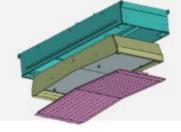


In close cooperation with our advanced materials provider, HELLER's new low temperature catalyst can help remove flux during reflow resulting in a clean process chamber.

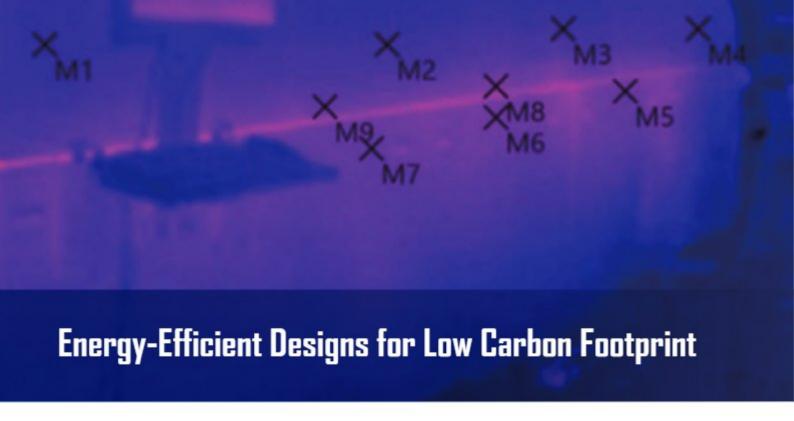
Pit-Stop features are an innovative way to reduce PM times by reducing overall oven downtimes. Parts involved with Pit-Stop features can be removed and exchanged without cooling down the oven, so production can be resumed right after the exchange.



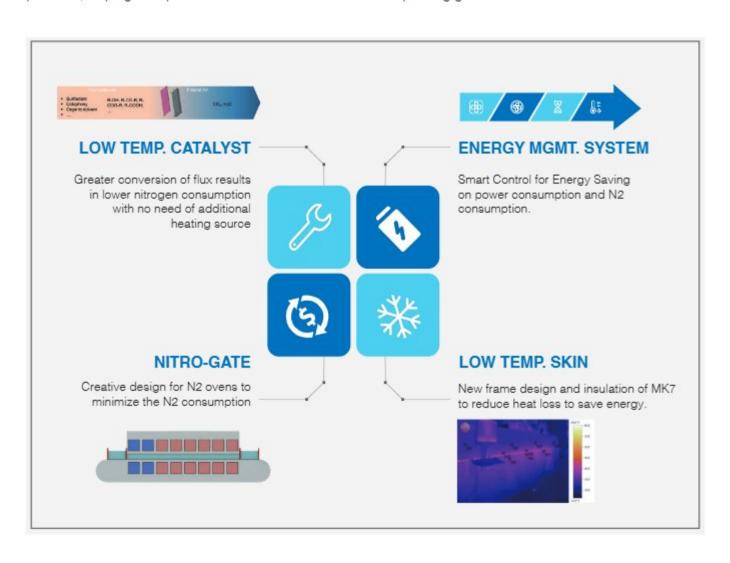
Quick Release and Anti-Flux Dripping Design



The quick release cooling grill with anti-flux dripping design simplify flux cleanup in the cool zones, further reducing overall PM effort.



Heller takes low-carbon, green and sustainable development as the company's long-term goals, while meeting the technical requirements of customers, and spares no effort to apply green environmental protection technology to products, helping enterprises and the world to achieve carbon peaking goals.





Support Customer MES Digitalization is changing all areas of our lives. HELLER Interface and manufacturing is no different. Manufac-MES turing companies must move with this trend by adopting smart manufacturing process-Support Equipment Protocol es in order to stay competitive. While the ASM Interface, Pana ILNB, FWI Link ultimate goals of fast delivery, low cost **Equipment Protocol** and high quality have remained unchanged, the management and analysis of data from production, Support Industry Protocol process and equipment is now Industry Protocol IPC Hermes 9852, IPC CFX, SECS/GEM essential. HELLER understands this, and our software tools fully support smart manufac-Smart Machine turing and Industry 4.0. **Smart Machine** Digitalization for monitoring HELLER365 (Traceability)
 Energy Managemeznt System Building Blocks for smart factory

HELLER ovens are smarter ever than before with integrated HW & SW. This enables operators to monitor the process in real-time to quickly improve product quality and yield, while reducing costs. HELLER 365 provides live oven monitoring of the thermal process on board level to ensure they are under control and within spec. All data is saved which allows users to look back at previous production and process data.





Electronics Manufacturers demand a high level of productivity—providers are pushed to offer better results while maintaining profitability. To grow your business, you need a flexible system that can accommodate products and applications for SMT and Semicon. The MK7 is capable to serve a wide range of products and applications, giving you a competitive advantage to expand into new lines of business.



Compatible and configurable for your specific need



Less downtime for more productivity



Lower delta T's and easily adjusted thermal profile



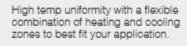
Reduced energy and Nitrogen consumption at any PPM level



Fast response to heat transfer for any product, delivering the highest soldering quality



Providing oven data to superior SW for smart data analysis and smart control



Heated Zones + Cooling Zones

High parallelism, and Low vibration. Single, dual and multiple lane configurations available with options CBS or mesh belt.

Transportation

Heater modules available in either 10" and 12" in length, and either 30" or 34" in width, to meet the needs of different applications.

Heaters and Modules



Cooling system

Efficient cooling system with air cooling and optional water box for extra support.

Flux Management

Boards stay clean and dry with multiple flux management options based on flux consumption, including air, water and pyrolysis.

...And More

Additional options include cleanroom capability (class10k &1k), heavy mass loading, and high-temp processing (400oC)

MK7 Systems Meet Your Total Requirements

	1505MK7*	1707MK7	1809MK7	1810MK7*	1826MK7	1913MK7	1936MK7	2043MK7(3C)	2043MK7(4C)
Basic Data			in the second	4			Article Control		
Length (mm)	2,000(Air)	3,615	4,660	4,660	4,660	5,900	5,900	6,780	7,225
Width (mm)	1,490	1,490	1,490	1,490	1,490	1,490	1,490	1,490	1,490
Height (mm)	1,480	1,480	1,480	1,480	1,480	1,480	1,480	1,480	1,480
Weight (kg)**	1,200(Air)	1,750	2,250	2,350	2,200	2,950	2,800	3,450	3,765

Power and N2									
Power Inputs		208/240/380/400/415/440/480 VAC							
Max Current Draw		100Amp				130Amp @ 208/240V 100Amp @ 380/400/415/440/480V			
Continuous Power kW	6 - 8	7 - 12	7.5 - 16	7.5 - 18	8 - 14	9 -15	9 -15	13 - 20	13 - 20
N ₂ Supply Pressure (bar)	5-7								
N ₂ Operating Pressure (bar)	8								
Typical N ₂ Consumption***	500-700SCFH								

Heating and Cooling									
Heating Zones*	5	7	9	10	8	13	10	13	13
Heating Length (mm) *	1,345(Air)	1,920	2,500	2,750	2,710	3,560	3,600	4,390	4,500
Cooling Zones*	1	1	2	2	2	3	3	3	4
Cooling Length (mm)*	340	825	1090	840	880	1,270	1,240	1,320	1,670
Max.Temp (°C) *	350	350	350	350	350	350	350	350	350
Resolution of Temp. Controller(°C)				±0.1				
Profile Change Time (min)					5 - 15				

PCB Support		
Single Lane / MeshBelt*	50 - 560 , Option 50 - 610	
Dual Lane in Single Lane Mode*	50 - 400, Option 50 - 450	
Dual Lane in Dual Lane Mode*	50 - 225, Option 50 - 250	
Dual Lane Rails*	FMMM, FMMF, FMFM	
PCB Direction	L to R, R to L	
PC8 Top/Bottom Clearance (mm)*	Meshbelt: Top 58 Chain: ±29 & ±35	
Transportation Height (mm)*	Mesh belt: 930+/-60 Chain: 980+/-60, Option 900+/-60	
Conveyor Speed (mm/min)*	250 - 1,880	
Length of PCB Support Pins	4.75	
Auto Lubrication System	s	
Power Width Adjustment	s	
KIC Profiling Software	S	

** Oven weight varies upon actual configurations

** Varies with PPM, PCB size and oven configuration

Please note specifications for air ovens and N2 ovens may vary, and specifications of the actual product may vary from those listed in this promotional brochure due to product improvements or technical updates. For the latest information, please contact us.



Why Partner with HELLER?

MARKET LEADER

In Soldering and Curing Systems for SMT and Semi-Con. Worldwide Footprint - Be Global and Local ("Glocal")



ADVANCED TECHNOLOGY

Extendable to Future Applications Extensive Library of Tested Designs Generated from Semi-Con

STRONG CAPABILITY

To Innovate and Customize Quickly for Applications. Easy to Work With

GREEN TECHNOLOGY

Environmentally Conscious / Sustainability Focus and Designs



HELLER Industries was founded in 1980 and pioneered convection reflow soldering in the 1980s. Over the years, Heller has partnered with its customers to continually refine the systems to satisfy advanced applications requirements. By embracing challenge and change, Heller has earned the position of World Leader in Reflow Technology

With the Largest Engineering Team in the industry, HELLER has the capability to quickly deliver special thermal processing solutions and provide your businesses with a competitive advantage!



A Continuous Investment in Engineering Manpower Drives the Technology...

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